EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"US 20060257575"	US-PGPUB; USPAT; USOCR; DERWENT	ADJ	ON	2011/10/20 14:53
L3	76	ink with (epoxyacrylate or polyestertetraacrylate or urethanacrylate or diacrylate oligomer or benzildimethylketal)	US-PGPUB; USPAT; USOCR; DERWENT	ADJ	ON	2011/10/20 15:26
L4	30	ink with (epoxyacrylate or polyestertetraacrylate or urethanacrylate or diacrylate oligomer or benzildimethylketal) and @PY<"2004"	US-PGPUB; USPAT; USOCR; DERWENT	ADJ	ON	2011/10/20 15:26
L5	190	ink with (epoxy acrylate or polyester tetraacrylate or urethan acrylate or diacrylate oligomer or benzildimethylketal) and @PY<"2004"	US-PGPUB; USPAT; USOCR; DERWENT	ADJ	ON	2011/10/20 15:29
L6	104	ink with (epoxy acrylate or polyester tetraacrylate or urethan acrylate or diacrylate oligomer or benzildimethylketal) and @PY<"2004" and UV	US-PGPUB; USPAT; USOCR; DERWENT	ADJ	ON	2011/10/20 15:29
L7	58	ink with (epoxy acrylate or polyester tetraacrylate or urethan acrylate or diacrylate oligomer or benzildimethylketal) and @PY<"2004" and UV cur$4	US-PGPUB; USPAT; USOCR; DERWENT	ADJ	ON	2011/10/20 15:29
L8	7	topcoat$4 with (epoxy acrylate or polyester tetraacrylate or urethan acrylate or diacrylate oligomer or benzildimethylketal) and @PY<"2004"	US-PGPUB; USPAT; USOCR; DERWENT	ADJ	ON	2011/10/20 15:30
L9	18	ink with (epoxy acrylate or polyester tetraacrylate or urethan acrylate or diacrylate oligomer or benzildimethylketal) and @PY<"2004" and UV cur$4 and metal$5 with substrate	US-PGPUB; USPAT; USOCR; DERWENT	ADJ	ON	2011/10/20 15:35
L10	2	"20030124339".pn.	US-PGPUB; USPAT; USOCR; DERWENT	ADJ	ON	2011/10/20 15:42
S1	1	("6548121").PN.	USPAT; USOCR	OR	OFF	2009/02/19 16:58
S2	1180	"ciba specialty chemicals corporation".as.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:03

S3	5	"ciba specialty chemicals corporation".as. and strongly adherent coatings	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:04
S4	5	"ciba specialty chemicals corporation".as. and strongly adherent coating	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:04
S5	1	10/566743.app.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/19 18:37
S6	1	("7455891").PN.	USPAT; USOCR	OR	OFF	2009/02/20 11:00
S7	8	(("7455891") or ("6251963") or ("6486228") or ("6515051") or ("6803392") or ("6733847") or ("6548121") or ("6368362")).PN.	USPAT; USOCR	OR	OFF	2009/02/20 11:09
S8	9	(("7455891") or ("6251963") or ("6486228") or ("6515051") or ("6803392") or ("6733847") or ("6548121") or ("6368362") or ("6399805")).PN.	USPAT; USOCR	OR	OFF	2009/02/20 11:14
S9	108	("3669951" | "3936305" | "4082679" | "4199421" | "4226763" | "4246315" | "4275004" | "4278589" | "4292152" | "4298738" | "4315848" | "4324744" | "4347180" | "4385109" | "4466993" | "4533652" | "4567106" | "4681905" | "4684679" | "4684680" | "4710523" | "4737593" | "4792632" | "4861916" | "4868246" | "4965294" | "4990364" | "5053246" | "5080994" | "5106891" | "5108835" | "5116534" | "5153284" | "5166355" | "5168087" | "5196142" | "5218009" | "5250698" | "5252403" | "5278314" | "5280124" | "5292890" | "5330539" | "5360850" | "5399770" | "5436349" | "5456728" | "5472992" | "5504236" | "5516914" | "5549847" | "5554760" | "5563242" | "5574166" | "5607987" | "5646088" | "5935900" | "5942290" | "5955514" | "5990189" | "6099122" | "6190423" | "6329445" | "6344505" | "6361925" | "6376065" | "6399805" | "6407254" | "6548121" | "6733847").PN. OR ("6251963" | "6368362" | "6399805" | "6486228" | "6515051" | "6548121" | "6733847" | "6803392" | "7455891").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/02/20 11:21
S10	15	("4199421" | "4246315" | "4466993" | "4567106" | "4990364" | "5053246" | "5252403" | "6099122" | "6548121" | "6733847").PN. OR ("6548121" | "6733847" | "7455891").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/02/20 11:22
S11	21169	427/533,535,536,517,407.1-412.5,532-559,517,509,512,513,517,518,519,520,535,536,538,551,553,554,556,407.2,409,412,412.1,419.2.ccls. or 430/311.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 11:27
S12	5299	427/533,509.ccls. or 430/311.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 11:27
S13	211	(adhere$4 or adhesion or glu$3 or bond$3) with metallized with (organic or polymer) with substrate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 12:30
S14	139	(adhere$4 or adhesion or glu$3 or bond$3) with metallized with (organic or polymer) with substrate and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 12:30

S15	13	(adhere$4 or adhesion or glu$3 or bond$3) with metallized with (organic or polymer) with substrate and @PY<"2004" and S11	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 12:30
S16	7	circuit and photoinitiator with adhesion with metal	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 16:56
S17	183	circuit and photoinitiator with adhesion and (metal or copper)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:11
S18	13	circuit and photoinitiator with adhesion with (metal or copper)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:11
S19	613	circuit and photoresist with adhesion with (metal or copper)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:18
S20	283	circuit and photoresist with adhesion with (metal or copper) and plasma	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:18
S21	47	circuit and photoresist with adhesion with (metal or copper) with plasma	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:19
S22	0	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink$3 or UV) with adhesion with (metal or copper) with plasma	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:34
S23	0	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink$3 or UV) and adhesion with (metal or copper) with plasma	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:34
S24	1116	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink$3 or UV)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:35

S25	46	solder mask with (photopolymerizable or photoresist or photoinitiator or light sensitive or crosslink$3 or UV) with adhesion	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:35
S26	10	solder mask with UV with adhesion	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:40
S27	2	"20030129322".did.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 17:42
S28	13	solder mask with (cvd or evaporate or pvd)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:38
S29	692	solder with (cvd or evaporate or pvd)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:41
S30	5	solder with (cvd or evaporate or pvd) with (photopolymerizible or UV or photoinitiator or photoresist)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:43
S31	149	solder with (cvd or evaporate or pvd) and (photopolymerizible or UV or photoinitiator or photoresist)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:44
S32	12645	metal with (cvd or evaporate or pvd) and (photopolymerizible or UV or photoinitiator or photoresist)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:44
S33	45	solder with (cvd or evaporate or pvd) and (photopolymerizible or UV or photoinitiator or photoresist) and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:44
S34	580	circuit board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) and (photopolymerizible or UV or photoinitiator or photoresist) and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:57

S35	25	circuit board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) with (photopolymerizible or UV or photoinitiator or photoresist) and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:57
S36	3	wiring board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) with (photopolymerizible or UV or photoinitiator or photoresist) and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 18:58
S37	121	circuit board and (metal or solder or contact or electrode or copper) with (cvd or evaporate or pvd) and (photopolymerizible or UV or photoinitiator or photoresist) and @PY<"2004" and cmp	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/20 19:05
S38	1	("6524950").PN.	USPAT; USOCR	OR	OFF	2009/02/20 19:21
S39	600	photoresist with (lift off or liftoff) and polymer$2 with substrate and metal	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:24
S40	189	photoresist with (lift off or liftoff) and polymer$2 with substrate and metal and @PY<"2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:24
S41	12	photoresist with (lift off or liftoff) and polymer$2 with substrate and metal and develop$3 with (solvent or mechanical$3)and dry with (oven or IR or hot gas$2 or microwave or roller) and @PY<"2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:25
S42	0	photoresist with (lift off or liftoff) and flexible with substrate and metal and develop$3 with (solvent or mechanical$3)and dry with (oven or IR or hot gas$2 or microwave or roller) and @PY<"2003"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:34
S43	0	photoresist with (lift off or liftoff) and flexible with substrate and metal and develop$3 with (solvent or mechanical$3)and dry with (oven or IR or hot gas$2 or microwave or roller) and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:34
S44	73	photoresist with (lift off or liftoff) and flexible with substrate and metal and develop$3 and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 12:34
S45	1721	(lithography or photoresist) with (lift off or liftoff) and (polymer$2 or metal$3 or glass or metal oxide) with substrate and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 13:42

S46	132	(lithography or photoresist) with (lift off or liftoff) and (polymer$2 or metal$3 or glass or metal oxide) with substrate and (sputter or evaporate) with (metal or half-metal) and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 13:43
S47	265	427/98.5.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 14:01
S48	95	427/98.5.ccls. and (resist or photoinitiator)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 14:02
S49	26	427/98.5.ccls. and (resist or photoinitiator) and plasma	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 14:03
S50	2	10/502208.app.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/02/23 15:36
S51	2	"5320933".pn.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/09/27 14:15
S52	18699	"circuit board" with ceramic	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/09/27 14:34
S53	267	"circuit board" with ceramic with metallized	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/09/27 14:35
S54	66	("circuit board" with ceramic with metallized).ab.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/09/27 14:35
S55	59	("circuit board" with ceramic with metallized).ab. and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/09/27 14:35

S57	1273	cur$3 with ($radiation or $radiated radiation or UV or ultraviolet or ultra violet) with primer	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/09/27 17:32
S58	29	cur$3 with ($radiation or $radiated radiation or UV or ultraviolet or ultra violet) with primer with plasma	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/09/27 17:32
S59	2	"US 20070245956"	US-PGPUB; USPAT; USOCR; DERWENT	ADJ	ON	2009/09/28 10:46
S60	73514	(adhere$4 or adhesion or glu$3 or bond$3 or prime$1) with metal$6 with substrate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/18 16:24
S61	274	(adhere$4 or adhesion or glu$3 or bond$3 or prime$1) with metal$6 with photoinitiator	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/18 16:25
S62	127	(adhere$4 or adhesion or glu$3 or bond$3 or prime$1) with metal$6 with photoinitiator and @PY<"2004"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/18 16:26
S63	1	wo-0158971-A2.did.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/27 15:47
S64	2	"20040011288".pn.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/27 16:15
S65	1	("7112351").PN.	USPAT; USOCR	OR	OFF	2011/02/02 13:58
S66	1	("4233130").PN.	USPAT; USOCR	OR	OFF	2011/02/02 14:02
S67	1	("6797428").PN.	USPAT; USOCR	OR	OFF	2011/04/22 16:02
S68	64	(adhere$4 or adhesion or glu$3 or bond$3 or prime$1) with polymer$2 with layers with photoinitiator and metal$6 with substrate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/04/22 17:39

S69	0	(adhere$4 or adhesion or glu$3 or bond$3 or prime$1) with polymer$2 with layers with photoinitiator and metallized polymer with substrate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/04/22 17:40
S70	0	polymer$2 with layers with photoinitiator and metallized polymer with substrate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/04/22 17:40
S71	29	polymer$2 with layers with photoinitiator and metallized with substrate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/04/22 17:40
S72	382	427/511.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/10/19 12:24
S73	128	427/511.ccls. and metal$6 with (substrate or surface)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/10/19 12:25
S74	2319	427/409-410.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/10/19 12:31
S75	403	metal with primer with ink	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/10/19 17:30
S76	131	metal$3 with substrate with primer with ink	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/10/19 17:31
S77	15	metal$3 with substrate with primer with ink and photoinitiator	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/10/19 17:33
S78	2	"20020183413".pn.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2011/10/20 13:21

EAST Search History (Interference)

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10/ 20/ 2011 3:59:39 PM
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